

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Original) An exposure apparatus that exposes a substrate via a projection optical system, the apparatus comprising:
 - a substrate stage that can move with the substrate mounted; and
 - a measurement section that has a plate on which a liquid is supplied and performs measurement related to the exposure via the projection optical system and the liquid, wherein the apparatus is configured so that at least a part including the plate that constitutes the measurement section can be exchanged.
2. (Original) The exposure apparatus of Claim 1 wherein the measurement section consists of a measurement unit that has at least a part of the unit arranged on a part of the substrate stage, and some of the components that include at least the plate that constitutes the measurement section unit is attached freely detachable to the substrate stage.
3. (Original) The exposure apparatus of Claim 1 wherein the measurement section comprises
 - a measurement stage main body that can move within a two-dimensional plane independently from the substrate stage, and
 - a measurement table main body that holds the plate.
4. (Original) The exposure apparatus of Claim 3 wherein the plate is held detachable from the measurement table main body.
5. (Original) The exposure apparatus of Claim 4, the apparatus further comprising: a leveling table attached on the measurement stage main body, wherein the measurement table main body is supported finely movable on the leveling table.
6. (Original) The exposure apparatus of Claim 5 wherein

the leveling table can be driven in directions of six degrees of freedom, and
the measurement table main body can be driven in directions of three degrees of
freedom within a horizontal plane.

7. (Original) The exposure apparatus of Claim 3, the apparatus further comprising:
a self-weight compensation mechanism that compensates weight of the measurement
table main body.

8. (Original) The exposure apparatus of Claim 1 wherein
at least one fiducial mark and at least one pattern used for measurement is formed on
the plate, and

the measurement section has a light-receiving system that receives exposure light
irradiated on the plate via the projection optical system, via the pattern used for measurement.

9. (Original) The exposure apparatus of Claim 8 wherein
a plurality of types of patterns used for measurement are formed on the plate, and
the measurement section has a plurality of the light-receiving systems that correspond
to the pattern used for measurement.

10. (Original) The exposure apparatus of Claim 9 wherein
the plurality of types of patterns used for measurement include at least one of an
aperture pattern used for aerial image measurement, a pinhole aperture pattern used for
irregular illumination measurement, an aperture pattern used for illuminance measurement,
and an aperture pattern used for wavefront aberration measurement.

11. (Original) The exposure apparatus of Claim 1, the apparatus further comprising:
at least one substrate stage different from the substrate stage on which the substrate is
mounted.

12. (Original) The exposure apparatus of Claim 1, the apparatus further comprising:
a control unit that executes measurement by the measurement section according to an
exchange timing of a substrate on the substrate stage.

13. (Original) The exposure apparatus of Claim 12 wherein
the control unit executes measurement of specific types, dividing the measurement
into a plurality of times according to the exchange timing of the substrate.

14-37. (Canceled)

38. (New) A device manufacturing method that includes a lithography process in
which a device pattern is transferred onto a substrate using the exposure apparatus according
to Claim 1.

39. (New) An exposure apparatus that exposes a substrate via a projection optical
system, the apparatus comprising:

a substrate stage that can move with the substrate mounted; and
a measurement section that has a plate on which mirror-polishing is applied on at least
one edge surface, and performs measurement related to the exposure via the projection optical
system, wherein

the apparatus is configured so that at least a part including the plate that constitutes
the measurement section can be exchanged.

40. (New) The exposure apparatus of Claim 39 wherein
the measurement section consists of a measurement unit that has at least a part of the
unit arranged on a part of the substrate stage, and some of the components that include at least
the plate that constitutes the measurement section unit is attached freely detachable to the
substrate stage.

41. (New) The exposure apparatus of Claim 39 wherein
the measurement section comprises
a measurement stage main body that can move within a two-dimensional
plane independently from the substrate stage, and
a measurement table main body that holds the plate.

42. (New) The exposure apparatus of Claim 41 wherein
the plate is held detachable from the measurement table main body.

43. (New) The exposure apparatus of Claim 42, the apparatus further comprising:
a leveling table attached on the measurement stage main body, wherein
the measurement table main body is supported finely movable on the leveling table.

44. (New) The exposure apparatus of Claim 43 wherein
the leveling table can be driven in directions of six degrees of freedom, and
the measurement table main body can be driven in directions of three degrees of
freedom within a horizontal plane.

45. (New) The exposure apparatus of Claim 42, the apparatus further comprising:
a self-weight compensation mechanism that compensates weight of the measurement
table main body.

46. (New) The exposure apparatus of Claim 39 wherein
at least one fiducial mark and at least one pattern used for measurement is formed on
the plate, and
the measurement section has a light-receiving system that receives exposure light
irradiated on the plate via the projection optical system, via the pattern used for
measurement.

47. (New) The exposure apparatus of Claim 46 wherein
a plurality of types of patterns used for measurement are formed on the plate, and
the measurement section has a plurality of the light-receiving systems that correspond
to the pattern used for measurement.

48. (New) The exposure apparatus of Claim 47 wherein
the plurality of types of patterns used for measurement include at least one of an
aperture pattern used for aerial image measurement, a pinhole aperture pattern used for
irregular illumination measurement, an aperture pattern used for illuminance measurement,
and an aperture pattern used for wavefront aberration measurement.

49. (New) The exposure apparatus of Claim 39, the apparatus further comprising:

at least one substrate stage different from the substrate stage on which the substrate is mounted.

50. (New) The exposure apparatus of Claim 39, the apparatus further comprising:
a control unit that executes measurement by the measurement section according to an exchange timing of a substrate on the substrate stage.

51. (New) The exposure apparatus of Claim 50 wherein
the control unit executes measurement of specific types, dividing the measurement into a plurality of times according to the exchange timing of the substrate.

52. (New) A device manufacturing method that includes a lithography process in which a device pattern is transferred onto a substrate using the exposure apparatus according to Claim 39.

53. (New) An exposure apparatus that exposes a substrate via a projection optical system, the apparatus comprising:
a substrate stage that can move with the substrate mounted;
a measurement section that has a plate that can be exchanged, and performs measurement related to the exposure via the projection optical system; and
a detection unit that detects an exchange timing of the plate.

54. (New) The exposure apparatus of Claim 53 wherein
at least one fiducial mark and at least one pattern used for measurement is formed on the plate, and
the measurement section has a light-receiving system that receives exposure light irradiated on the plate via the projection optical system, via the pattern used for measurement.

55. (New) The exposure apparatus of Claim 54 wherein
a plurality of types of patterns used for measurement are formed on the plate, and
the measurement section has a plurality of the light-receiving systems that correspond to the pattern used for measurement.

56. (New) The exposure apparatus of Claim 55 wherein
the plurality of types of patterns used for measurement include at least one of an
aperture pattern used for aerial image measurement, a pinhole aperture pattern used for
irregular illumination measurement, an aperture pattern used for illuminance measurement,
and an aperture pattern used for wavefront aberration measurement.

57. (New) The exposure apparatus of Claim 53, the apparatus further comprising:
at least one substrate stage different from the substrate stage on which the substrate is
mounted.

58. (New) The exposure apparatus of Claim 53, the apparatus further comprising:
a control unit that executes measurement by the measurement section according to an
exchange timing of a substrate on the substrate stage.

59. (New) The exposure apparatus of Claim 58 wherein
the control unit executes measurement of specific types, dividing the measurement
into a plurality of times according to the exchange timing of the substrate.

60. (New) A device manufacturing method that includes a lithography process in
which a device pattern is transferred onto a substrate using the exposure apparatus according
to Claim 53.

61. (New) An exposure method in which a substrate is exposed, the method
comprising:
an exchange process in which of a measurement section that performs measurement
related to the exposure via a plate on which a liquid is supplied, at least a part including the
plate is exchanged; and
an exposure process in which measurement related to the exposure is performed using
the measurement section after the exchange, and the substrate is exposed reflecting the
measurement results.

62. (New) An exposure method in which a substrate is exposed, the method
comprising:

an exchange process in which of a measurement section that performs measurement related to the exposure via a plate that has at least one edge surface mirror-polished, at least a part including the plate is exchanged;

a measurement process in which a position of the plate after the exchange is measured via the edge surface, and the measurement is performed using the measurement section; and

an exposure process in which the measurement results are reflected and the substrate is exposed.

63. (New) An exposure method in which a substrate is exposed, the method comprising:

a measurement process in which measurement is performed using a measurement section that performs measurement related to the exposure via a plate;

an exchange process in which an exchange timing of the plate is detected and the plate is exchanged; and

an exposure process in which the substrate is exposed with the measurement results reflected.